

IN THE CLAIMS

The current claims follow. For claims not marked as amended in this response, any difference in the claims below and the previous state of the claims is unintentional and in the nature of a typographical error.

1. (Currently Amended) For use in a semiconductor process, a ~~A~~ tool for lifting a chemical mechanical polishing (CMP) pad, the tool comprising:

a non-pivoted jaw structure having an upper jaw portion and a lower jaw portion, the lower jaw portion having outer and inner surfaces, wherein the inner surface is substantially flat and not parallel to the outer surface, the inner surface being operable to receive a portion of the CMP pad, wherein the CMP pad is used to polish a semiconductor wafer;

a first member pivotally coupled to the non-pivoted jaw structure; and

a second member pivotally coupled to the first member, the second member having a surface opposite to the inner surface of the lower jaw portion and operable for clamping the portion of the CMP pad against the inner surface when the first member is pivoted upwards.

2. (Original) The tool of claim 1, wherein the upper jaw portion has an arcuate lower surface.

3. (Previously Presented) The tool of claim 2, wherein the non-pivoted jaw structure is arcuate.

4. (Previously Presented) The tool of claim 1, wherein the non-pivoted jaw structure comprises a first half coupled to a second half.

5. (Previously Presented) The tool of claim 1, wherein the lower jaw portion comprises a substantially flat outer surface.

6. (Original) The tool of claim 1, wherein the first member comprises a cutout in which a portion of the second member is pivotally positioned.

7. (Original) The tool of claim 1, wherein the surface of the second member comprises a textured surface.

8. (Currently Amended) For use in a semiconductor process, a A chemical mechanical polishing pad removal tool, comprising:

a non-pivoted jaw structure having an upper jaw portion and a lower jaw portion, the upper jaw portion having an arcuate lower surface for contacting portions of an upper surface of ~~the~~ a chemical mechanical polishing pad used to polish a semiconductor wafer, the lower jaw portion

having outer and inner surfaces, wherein the inner surface is substantially flat and not parallel to the outer surface, the inner surface being spaced below and opposite to the arcuate lower surface for slidably receiving a portion of the chemical mechanical polishing pad;

a first member pivotally coupled to the non-pivoted jaw structure; and

a second member pivotally coupled to the first member, the second member having a surface projecting below the arcuate lower surface of the upper jaw portion and being opposite to the inner surface of the lower jaw portion, the second surface being operable for clamping the portion of the chemical mechanical polishing pad against the inner surface when the first member is pivoted upwards.

9. (Previously Presented) The tool of claim 8, wherein the non-pivoted jaw structure is arcuate.

10. (Previously Presented) The tool of claim 8, wherein the non-pivoted jaw structure comprises a first half coupled to a second half.

11. (Previously Presented) The tool of claim 8, wherein the lower jaw portion comprises a substantially flat outer surface.

12. (Original) The tool of claim 8, wherein the first member comprises a cutout in which a portion of the second member is pivotally positioned.

13. (Previously Presented) The tool of claim 12, comprising a cap coupled to the first member to laterally enclose the cutout.

14. (Original) The tool of claim 8, wherein the surface of the second member comprises a textured surface.

15. (Currently Amended) A chemical mechanical polishing pad removal tool; comprising:
a non-pivoted jaw structure having an upper jaw portion and a lower jaw portion, the upper jaw portion having an arcuate lower surface for contacting portions of an upper surface of ~~the a~~ chemical mechanical polishing pad used to polish a semiconductor wafer, the lower jaw portion having outer and inner surfaces, wherein the inner surface is substantially flat and not parallel to the outer surface, the inner surface being spaced below and opposite to the arcuate lower surface for slidably receiving a portion of the chemical mechanical polishing pad, the inner surface terminating at a lower end in a rounded end;

a handle pivotally coupled to the non-pivoted jaw structure; and

a member pivotally coupled to the handle, the member having a textured surface projecting below the arcuate lower surface of the upper jaw portion and being opposite to the inner surface of

the lower jaw portion, the textured surface being operable for clamping the portion of the chemical mechanical polishing pad against the inner surface when the handle is pivoted upwards.

16. (Previously Presented) The pad removal tool of claim 15, wherein the non-pivoted jaw structure is arcuate.

17. (Previously Presented) The pad removal tool of claim 15, wherein the non-pivoted jaw structure comprises a first half coupled to a second half.

18. (Previously Presented) The pad removal tool of claim 15, wherein the lower jaw portion comprises a substantially flat outer surface.

19. (Currently Amended) The pad removal tool of claim 15, wherein the handle comprises a cutout in which a portion of the ~~second~~ member is pivotally positioned.

20. (Currently Amended) The pad removal tool of claim 19~~5~~, comprising a cap coupled to the ~~first~~ member to laterally enclose the cutout.